

# CHAIRMAN'S STATEMENT

## 主席報告

### Results

We are pleased to report that ASM Pacific Technology Limited and its subsidiaries (the "Group" or "ASM") achieved a record turnover amounting to HK\$4,555,953,000 in the fiscal year ended 31 December 2006, representing an increase of 28.8% as compared with HK\$3,536,855,000 for the previous year. The Group's consolidated profit for the year is HK\$1,149,477,000, which is 35.2% higher than the previous year's consolidated profit of HK\$850,485,000. Basic earnings per share for the year amounted to HK\$2.97 (2005: HK\$2.21).

### Dividend

An interim dividend of HK\$0.70 (2005: HK\$0.50) per share and first special dividend of HK\$0.75 (2005: HK\$0.20) per share were paid in August 2006.

Having established a solid foundation in the microelectronics market over the years, ASM intends to further its organic growth path in the near term through enlarging its market share with diversified, high performance products. There is no short term need for major cash outlay and the Group has consistently generated significant positive cash flow from operations in each of the past ten years.

### 業績

謹此欣然報告，ASM Pacific Technology Limited 及其附屬公司（「集團」或「ASM」）於截至二零零六年十二月三十一日止年度錄得營業額創新高達港幣 4,555,953,000 元，與上年度港幣 3,536,855,000 元比較，增長 28.8%。本年度集團的綜合溢利為港幣 1,149,477,000 元，較上年度綜合溢利港幣 850,485,000 元增長 35.2%。是年度每股基本溢利為港幣 2.97 元（二零零五年：港幣 2.21 元）。

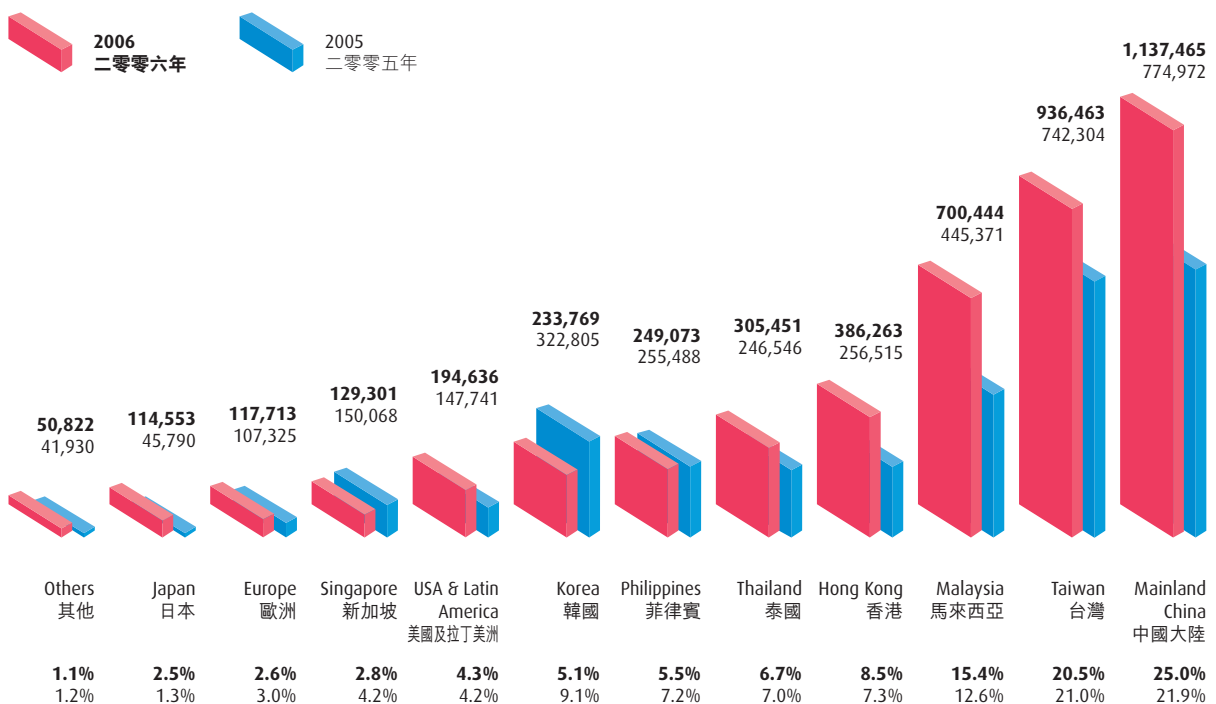
### 派息

中期股息每股港幣 0.70 元（二零零五年：港幣 0.50 元）及首次特別股息每股港幣 0.75 元（二零零五年：港幣 0.20 元）已於二零零六年八月派發。

憑藉多年來在微電子市場所建立的穩固基礎，ASM 未來將致力透過多元化及高性能的產品擴大市場佔有率，積極加快本體增長。集團在短期內沒有重大現金開支，並於過去十年持續於營運產生顯著正現金流量。

### Turnover by Geographical Location (HK\$'000)

#### 地域分類營業額（港幣千元）



### Dividend continued

In view of our strong liquidity and rising equity base, the Board of Directors have decided to recommend a final and second special dividend of HK\$1.00 (2005: HK\$1.00) per share and HK\$0.20 (2005: HK\$0.30) per share respectively payable on or around 30 April 2007, making a total dividend payment of HK\$2.65 (2005: HK\$2.00) per share for the year ended 31 December 2006, inclusive of HK\$0.95 (2005: HK\$0.50) per share of special dividend. This translates into a 89.4% dividend payout ratio for the current year profit; representing a prudent decision to return current excessive cash holdings to our shareholders while continuing to operate the Group with the optimum shareholders' funds.

### Review

The global semiconductor industry experienced solid growth in 2006, although the market somewhat weakened towards end of the year. Growth was primarily driven by consumer applications such as flat-panel displays, MP3 players and digital cameras. According to several leading industry analysts, the increase in sales of semiconductor devices in 2006 was in the range of 8 - 11%. As regards the semiconductor assembly and packaging equipment industry, the common view of the analysts is that it grew by 13 - 19% during the same period.

### 派息 續

在擁有充裕的流動資金和股本增加的情況下，董事會建議派發末期股息每股港幣 1.00 元 (二零零五年：港幣 1.00 元) 及第二次特別股息每股港幣 0.20 元 (二零零五年：港幣 0.30 元)，並將於二零零七年四月三十日左右派發。連同每股港幣 0.95 元 (二零零五年：港幣 0.50 元) 之特別股息，集團截至二零零六年十二月三十一日止年度全年合計每股派息為港幣 2.65 元 (二零零五年：港幣 2.00 元)，本年度派息率 89.4%，充分顯示集團決定將現有剩餘現金回饋股東時已作出審慎考慮，並預留適量的股東資金作集團營運之用。

### 業務回顧

儘管市場在年底前較為疲弱，全球半導體行業於二零零六年錄得穩固增長，主要由平面顯示器、MP3 機及數碼相機等消費產品的需求帶動。根據業內多位權威分析員表示，二零零六年半導體產品的銷售增長介乎 8 - 11%。至於半導體裝嵌及包裝設備行業，分析員普遍認為其銷售於同期增長為 13 - 19%。

### Turnover by Products (HK\$'Million)

產品分類營業額 (港幣百萬元)



2005  
二零零五年



2006  
二零零六年

#### Review continued

On the back of a good performance by the semiconductor industry in 2006, ASM had an exceptional year during which the Group set multiple new records. In fact, after a stellar turnover during the first half of 2006, we slightly bettered that performance in the second half, even in the face of some softening in the general market towards the end of the year. Both our equipment and leadframe businesses produced record turnovers, resulting in the Group attaining unprecedented levels of progress and profitability in many fields during the period.

Over the past few years, ASM has consistently outperformed its industry peers. We are pleased to have repeated this performance again in 2006, surpassing the estimated overall 13 - 19% growth in the assembly and packaging equipment industry with an increase of 25.1%. In doing so, we gained further market share and solidified our number one position in the global assembly and packaging equipment market, achieving a Group turnover of US\$587 million and net profit of HK\$1,149 million, both of which are new records for ASM. This represents 28.8% and 35.2% growth respectively over the previous year. Return on capital employed and on sales were 49.9% and 27.4%. Such a strong financial performance clearly reflects ASM's leadership position and the growing acceptance of ASM's products and services, which positions us well for the future. Our overall book-to-bill ratio was 1.0 for the year, representing net bookings over billings, a slight decrease year-on-year from the preceding year's record. Our ending order backlog as of 31 December 2006 was US\$103.9 million.

ASM has built a solid business foundation based on diversified products serving broad application markets. Our financial performance in recent years has clearly reflected the success of this strategy. With equipment revenue of US\$461 million, equivalent to 78.6% of the Group's turnover, ASM was again the top player in its industry, keeping the premier position we have held since 2002. We widened the gap between ourselves and the no. 2 player to US\$179 million, representing a lead of 63.4% over our closest rival. Significantly, our leadframe revenue further increased its contribution to the Group's turnover, growing by 44.8%, largely as a result of a strong gain in market share. This highlights the success of our efforts to further enhance our market position in the leadframes business.

#### 業務回顧 續

受惠於半導體行業蓬勃發展，集團於二零零六年創下多個新紀錄。繼營業額在二零零六年上半年大幅上升，集團表現並未受年底市場普遍疲弱所影響，營業額於下半年輕微上升。設備業務及引線框架業務的營業額同創新高，集團期內各項業務的發展及盈利能力均達至前所未有的高水平。

一如過去數年，ASM 持續超越同儕，集團欣然能於二零零六年再次延續佳績，裝嵌及包裝設備業務增長 25.1%，超越行業整體估計升幅 13 - 19%。同時，集團進一步擴大市場佔有率及鞏固其在全球裝嵌及包裝設備行業的第一位，營業額及溢利均刷新紀錄，分別達到 5.87 億美元及港幣 11.49 億元，較上年度增長 28.8% 及 35.2%。資本回報率及銷售利潤率分別為 49.9% 及 27.4%。集團強勁的財務表現充分反映 ASM 的領導地位，及其產品和服務的受歡迎程度與日俱增，有利推動集團的未來發展。本年度集團的整體訂貨對付運比率(以訂貨淨額除付運額計算)為 1.0，較去年同期輕微下跌。集團於二零零六年十二月三十一日的未完成訂單總值為 1.039 億美元。

ASM 透過為多個應用市場提供多元化產品，建立了穩固的業務基礎，而近年集團的卓越業績正充份證明這策略的成功。本年度集團設備業務的營業額為 4.61 億美元，佔集團營業額 78.6%，使 ASM 再次於行業中獨佔鰲頭，並穩佔自二零零二年以來行業第一位。集團更擴闊與佔行業第二位的競爭對手之收益差距至 1.79 億美元，高出 63.4%。更重要的是，集團引線框架業務亦成功擴大市場佔有率，營業額增長 44.8%，使其對集團的營業額有進一步的貢獻，反映集團銳意提高其於引線框架市場地位的努力取得顯著成果。

#### Review continued

We have actually achieved strong growth for many of our products. In particular, our die bonders continue to make great strides in gaining acceptance and acquiring further market share; we have retained our position as the world's top supplier of die bonders in 2006. Our CSP equipment business has also experienced a quantum leap in revenue and is now of significant size, no doubt demonstrating market acceptance and its growth into an integral part of the Company's product offerings.

Our dual head gold wire bonder is making major inroads into its market segment, a good example of the successful implementation of our Blue Ocean strategy. We also continue to hold a leading position in copper wire bonding technology. In addition, while global demand for flip chip bonders is still small compared to wire bonders, our flip chip bonders have further penetrated key IDM customer markets during the past year.

Our encapsulation equipment business saw substantial growth in particularly the demand for "package-on-package" (PoP) molding technology and we are now recognized as a market leader in PoP molding solutions. The growth in demand and our developing strength in this field put us on the radar of many prospective customers and this helped increase our market base. We continue to be strong in the field of CMOS Image Sensor (CIS) assembly lines and equipment, which highlights the success of our "total solution" approach to marketing our products. Similarly, we have also seen greater acceptance of our total solutions offerings for the micro-SD cards application.

#### 業務回顧 續

集團多項產品均錄得強勁增長，尤其管芯焊機的接受程度及市場佔有率均大幅提升。於二零零六年，ASM 繼續成為管芯焊機的全球最大供應商。集團的 CSP 設備業務的營業額經歷大幅上升，為集團營業額作出顯著貢獻，無疑證明該產品廣受市場認同，並已成為集團產品系列不可或缺的一部份。

集團的雙頭金線焊線機大幅拓展其市場，是集團成功推行藍海策略 (Blue Ocean strategy) 的最佳例子。集團亦保持其於銅線焊線技術的領先優勢。此外，雖然全球市場對覆晶焊機的需求相對焊線機仍較低，集團的覆晶焊機在過往年度已進一步滲入主要的集成裝置製造商市場。

集團的塑封設備業務大幅增長，尤其客戶對多層包裝 (PoP) 塑封工序技術的需求顯著提升。集團現已被視為多層包裝塑封工序解決方案市場的領導者。隨著市場需求上升及集團的研發優勢，將有助吸納更多客戶，擴大其市場基礎。集團的 CMOS 影像感應組件裝嵌線及設備業務表現持續強勁，證明集團提供「全面解決方案」的市場推廣策略十分成功。同時，集團為微型 SD 卡應用而提供的全面解決方案亦廣受歡迎。

#### Liquidity and financial resources

The Group's shareholders' funds increased slightly to HK\$2,562,074,000 as at 31 December 2006 (2005: HK\$2,393,534,000). As there were no long term borrowings, gearing of the Group was zero, the same as for the past seven years.

Although HK\$1,064.4 million was paid as dividends and HK\$208.7 million was spent in capital investments during the twelve-month period, due to good control of working capital and strong positive cash flow from operation, cash on hand as of 31 December 2006 was HK\$914,681,000 (2005: HK\$728,927,000). In fact, a good portion of the capital investments were funded by the current year's depreciation of HK\$168.4 million.

There was no bank borrowing as of 31 December 2006. Current ratio was 2.84, with a debt-equity ratio of 36.1%. With no short-term needs and an on-going positive cash flow from organic growth operation, these figures permit ASM management to recommend a sustained high level of dividend to return excessive cash holdings to our shareholders. While account receivables have been tightly monitored during the year, with record billings there was an improvement to 71.1 days sales outstanding (2005: 88.2 days).

The Group has minimal currency exposure as the majority of all sales were denominated in U.S. dollars. On the other hand, the disbursements were mainly in U. S. dollars, Hong Kong dollars, Singapore dollars and Renminbi. The limited yen-based receivables were offset by some accounts payables in yen to Japanese vendors.

#### Human resources

ASM places strong emphasis on both recruiting and retaining high calibre employees, not only through competitive remuneration packages but also by committing ourselves to specialized yet demanding staff development and training programs. In general, salary review is conducted annually. In addition to salary payments, other benefits include contributions to provident fund schemes and medical subsidies. Discretionary bonus and bonus shares may be granted to eligible staff based on the Group's financial results and individual performance.

As of 31 December 2006, the total headcount of the Group worldwide was approximately 9,000 people.

#### 流動資金及財務狀況

於二零零六年十二月三十一日，集團的股東資金輕微上升至港幣 2,562,074,000 元(二零零五年：港幣 2,393,534,000 元)。如過去七年一樣，集團並沒有長期借貸，負債比率為零。

儘管派發了港幣 10.644 億元的股息，及於十二個月內投入了港幣 2.087 億元作為資本性投資，由於營運資金控制得宜及營運現金流入強勁，於二零零六年十二月三十一日，集團的現金結存達港幣 914,681,000 元(二零零五年：港幣 728,927,000 元)。事實上，集團主要的資本性投資乃由是年度港幣 1.684 億元的折舊所支付。

於二零零六年十二月三十一日，集團並沒有任何銀行借貸，流動比率為 2.84，股本負債比率則為 36.1%。由於集團短期內沒有重大開支，並從營運活動持續產生正現金流量，ASM 管理層建議持續派發高息以回饋剩餘現金予集團的股東。於年內，集團嚴格監控應收賬款水平，縱使期內付運量創新高，應收賬款週轉率仍改善至 71.1 天(二零零五年：88.2 天)。

集團主要之銷售貨幣單位為美元，因此匯率風險非常低。另一方面，集團主要以美元、港幣、新加坡幣及人民幣支付開銷。有限的日圓應收賬款足夠應付部份應付予日本供應商之賬款。

#### 人力資源

集團為招攬及保留人才不遺餘力。除與員工訂立具競爭力的薪酬制度外，集團亦為員工提供專門並優秀的培訓計劃及發展機會。整體而言，集團每年會進行一次薪金調整。除薪金外，集團亦提供退休供款計劃及醫療津貼等其他福利。此外，視乎集團的業績及個別員工的表現，集團將分發花紅及紅股予應嘉許之員工。

於二零零六年十二月三十一日，集團於全球聘用約 9,000 名員工。

#### Prospects

An improving job market in major countries and healthy economic growth going forward should contribute to stronger demands for semiconductor devices. There is no doubt that the demand for consumer electronic products continues to be the driver of growth in the semiconductor industry. ASM is well-positioned to take advantage of such consumer products-led growth as IC packaging is seen as a technology enabler for consumer applications. The semiconductor industry is forecast to grow by another 9 - 11% in 2007. Similar growth is projected for 2008.

After strong growth experienced in 2006, the global assembly and packaging equipment industry is projected to consolidate with at best single digit growth and possibly even a single digit contraction in 2007. However, strong growth of between 14 - 26% is projected by some industry analysts for 2008. This is a reflection of shorter industry cycles that have greatly reduced magnitudes of fluctuation and an overall positive trend leading to a steady growth in the industry up to and including 2009.

It is generally expected that the equipment industry will grow at a slower pace at the start of 2007, and it is anticipated that the first quarter may also be a softer period for ASM. However, the industry is expected to experience a turnaround and start to improve in the second quarter, and we will prepare ourselves accordingly to take advantage of such improvement. Overall, whilst we may not equal some of the new record levels set in 2006, we definitely expect in 2007 to be able to further build upon our strengths in preparation for future growth.

ASM's solid business success has always been built upon a number of sturdy supporting pillars. Strategically, we have an extensive marketing network that focuses on customers' packaging challenges. We have been responsive to the needs of the market, and have successfully managed to capture opportunities presented by strong demand. Our vertical integration strategy and strategic choice of low cost manufacturing locations have proven to be successful. And with continuous cost reduction efforts and a constant drive for manufacturing-orientated design, ASM is committed to offering customers innovative products with good value propositions.

#### 展望

主要國家利好的就業情況及健康的經濟增長將帶動半導體產品的需求更趨強勁。市場對消費電子產品的需求乃半導體行業的增長動力。集成電路包裝作為消費應用的必要技術，ASM 已準備就緒，全面掌握由消費產品需求所帶來的商機。根據預測，二零零七年半導體行業將會增長 9 - 11%，而二零零八年升幅亦相若。

經過二零零六年的強勁升幅，市場預測全球裝嵌及包裝設備行業將於二零零七年整固，最佳將以單位數字增長，甚至錄得單位數字跌幅。不過，部份行業分析員預計二零零八年將錄得 14 - 26% 的強勁增長。這反映行業週期縮短，波動幅度大大減低，及整體利好趨勢將帶動行業穩步增長持續至二零零九年。

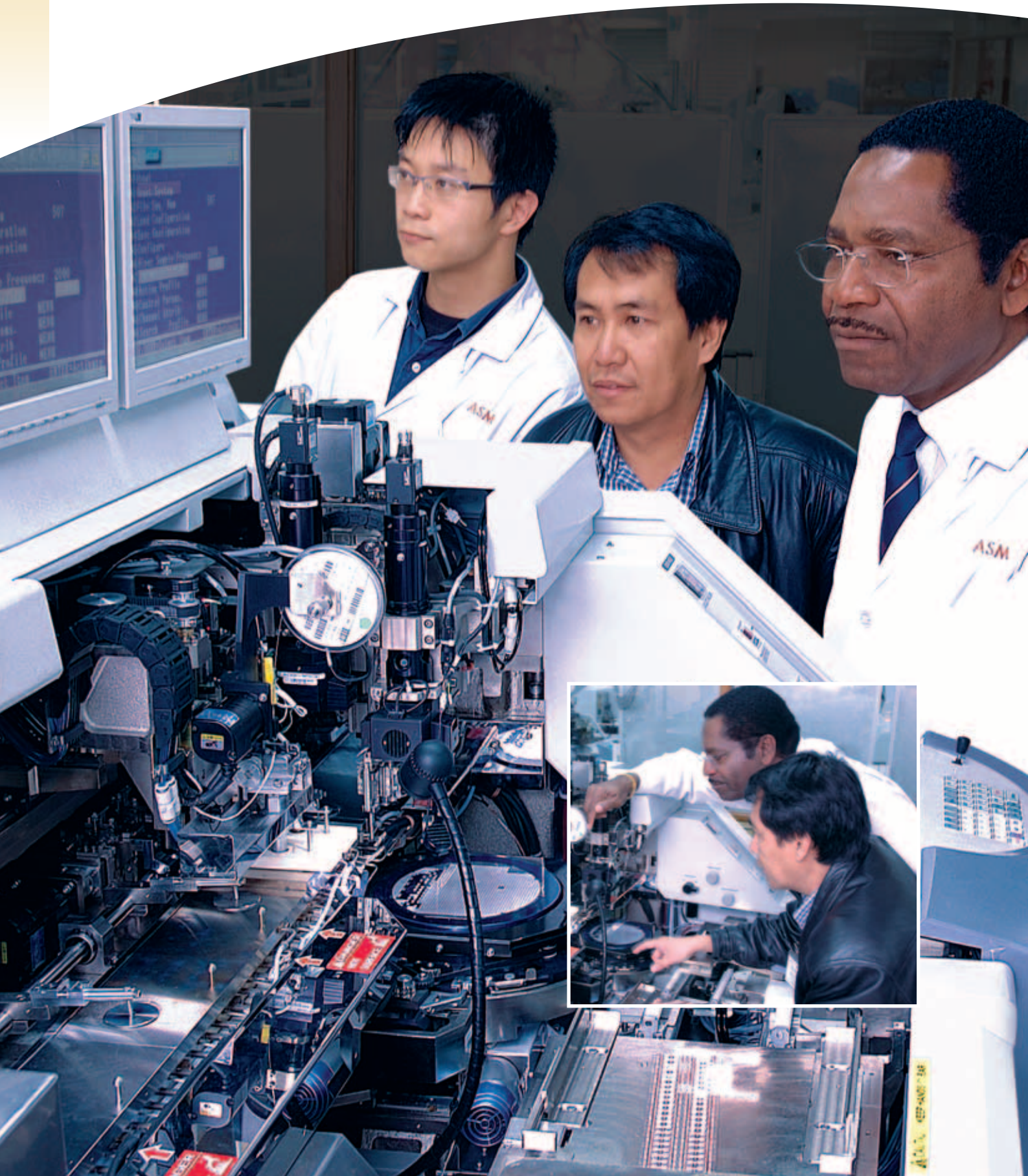
市場普遍預測設備行業於二零零七年初將以緩慢步伐增長，預期 ASM 的業務於首季亦相應放緩。然而，行業預計情況將於第二季逆轉及開始改善，故集團將積極部署以從中獲益。總括而言，即使集團未必能維持二零零六年所創下之歷史新高，亦可明確地預期於二零零七年將可進一步加強其優勢，為未來的業務增長作好準備。

ASM 的成功建基於多項重要策略。集團擁有龐大的市場推廣網絡，策略性地為客戶應付在包裝上的挑戰。集團緊貼市場需要，充分掌握龐大的市場需求。我們的垂直綜合策略及低成本生產基地的策略性選址均十分成功，集團並致力減省成本及採取以製造為導向的設計模式，承諾為客戶提供創新產品及高價值的方案。



Our die bonders continue to make great strides in gaining further market share, keeping us in the number one position since 2005.

集團的管芯焊機的市場佔有率持續大幅上升，並自二零零五年穩佔第一位。



#### Prospects continued

By undertaking packaging development programs with customers we have been able to offer them value-added services on top of our role as a leading equipment supplier: solution-selling has become a powerful marketing tool in this knowledge-based economy. Providing customers with innovative, total packaging solutions based on ASM's equipment and leadframes to meet their ever-expanding new product requirements has proven to be our most effective key to unlock customers' doors; the use of our PoP solutions in marketing our molding systems is a good example. This unique business strategy truly differentiates ASM from all our competitors, enabling us to further expand our business and to promote newly developed products. It has proven time and again to be useful in gaining market share as well as penetrating new markets.

When introducing new products, we emphasize product adjacency in order to achieve organic growth, ensuring that new models complement our existing product lines. We will continue to carry out our Blue Ocean strategy over the next few years by seeking to introduce new products for untapped and uncontested markets.

Leveraging our in-house enabling technologies, our product development efforts focus on injecting higher performance and lower cost of manufacturing into our new generation of products, while simultaneously continuing to rejuvenate our current generation equipment to achieve significant performance gains. To sustain ASM's continued leadership position and to build resilience in a dynamic industry, we intend to launch exciting new generations of die, flip chip and gold wire bonders in 2007. For instance, new Multi-Chip Module (MCM) and Chip-on-Glass (COG) bonders will be introduced. A new state-of-the-art gold wire bonder will update our current wire bonders with innovative features and a faster bonding speed to propel us to the forefront of wire bonding technology, while at the same time offering unprecedented user-friendliness. And a new single-strip molding system will further complement our popular sectional molding system.

#### 展望 續

綜合解決方案已成為知識型經濟下非常有力的市場推廣工具。透過與客戶共同研發包裝發展項目，集團在作為具領導地位的設備供應商的同時，更為客戶提供增值服務。透過應用 ASM 的設備和引線框架，集團為客戶提供創新及全面的包裝解決方案，以滿足客戶不斷擴展對新產品的需求，並證明此策略可成功開啟新客戶之門；而利用集團的多層包裝解決方案推廣其塑封工序系統乃另一個成功例子。此獨特的業務策略有助 ASM 從芸芸競爭對手中脫穎而出，進一步擴大業務及有效地推廣新開發產品。集團過去亦多次證明這項策略能有效提升市場佔有率及開拓新市場。

就開發新產品方面，集團著重產品間能相互配合，確保新型號產品可與現有產品相輔相成，從而達致本體增長。未來數年，集團將繼續推行藍海策略，旨在將新產品引入從未涉足及尚未出現競爭的市場。

憑藉我們自行研發的先進技術，集團的產品研發團隊將專注研發高性能及低生產成本的新產品，同時持續改良集團現有產品，大大提升其性能。為了在這個瞬息萬變的市場中鞏固其領導地位，和經得起行業起伏的考驗，集團計劃於二零零七年推出新一代的管芯、覆晶及金線焊線機，如新的多晶片組件 (MCM) 及晶片直接玻璃封裝 (COG) 焊接機。全新的金線焊線機將較現有焊線機配備更蕪新功能，焊接速度更快，同時操作更簡易，充分顯示集團走在焊線技術的最尖端。此外，全新的單片塑封工序系統將與我們廣受歡迎的分段塑封工序系統相互配合，進一步提升其效能。



Our leadframe business saw a 44.8% revenue growth in 2006 achieving record billings largely due to strong gain in market share and the maturing of our expanded operations in China.

引線框架業務成功擴大市場佔有率及在中國的運作擴展已趨成熟，營業額於二零零六年增長44.8%，創歷年新高。



### Appreciation

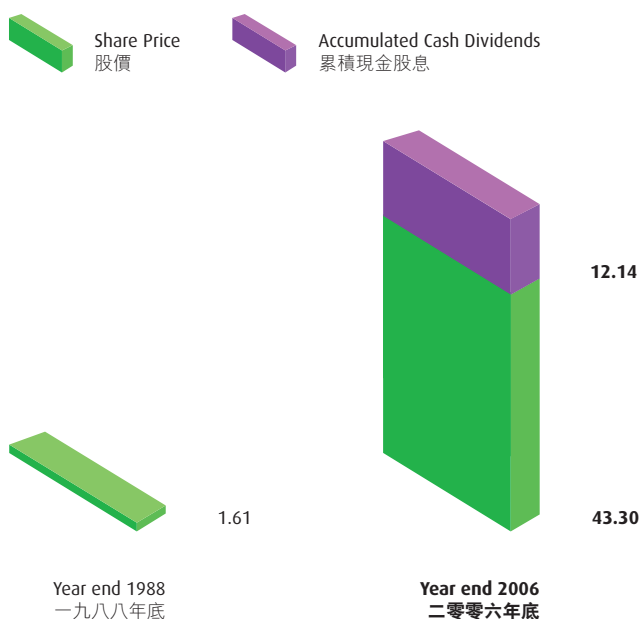
Management succession took place in 2006, representing a significant milestone in ASM's history. With good planning and execution, a highly competent team was groomed and nurtured to succeed our co-founder and Managing Director since inception, Mr. Patrick Lam. Patrick had led ASM for more than 31 profitable years during which he delivered excellent financial performance and returns to shareholders.

A shareholder who invested HK\$1.61 for each ASM share during the Initial Public Offering of the Company at the end of 1988 and held onto those shares until 31 December 2006 would have received HK\$12.14 in total as cash dividends over the years and enjoyed a gain of 26.9 times in share price (based upon ASM's closing share price of HK\$43.3 per share as at 31 December 2006).

This excellent financial result not only benefited our shareholders, it created many new jobs in the communities where ASM operates. It provided career growth opportunities, secure job environment and a stable income for ASM personnel and their families, offering an excellent environment for many capable ASM employees to achieve their own personal success. And perhaps most important of all, it allowed us to develop innovative, total product solutions that continue to deliver outstanding value propositions to our customers.

### Share Price and Cash Dividends Paid (HK\$)

#### 股價及已付現金股息 (港元)



### 致謝

集團管理層於二零零六年順利交接，是 ASM 一項重要的里程碑。透過完善的計劃及執行，集團已培植實力超卓的團隊，以繼承聯合創辦人兼董事總經理林師龐先生的職務。林先生帶領 ASM 31 個成果豐碩年頭，期間集團業績表現超卓，並為股東帶來可觀的回報。

集團於一九八八年底進行首次公開招股，若股東當時以每股港幣 1.61 元購入 ASM 的股份，並一直持有至二零零六年十二月三十一日，多年來已收取合共港幣 12.14 元的現金股息，股價亦已上升 26.9 倍(以 ASM 於二零零六年十二月三十一日每股港幣 43.3 元的收市價計算)。

卓越的業績表現不僅令股東得益，亦為 ASM 業務所遍及的地區創造大量就業機會。ASM 提供良好的就業晉升機會及理想的工作環境，為 ASM 員工及其家庭提供穩定的收入，並給予眾多具備卓越才華的 ASM 員工優秀的環境，讓他們振翅高飛。更重要的是，ASM 讓我們能夠開發創新及全方位的產品解決方案，充分滿足客戶需要。

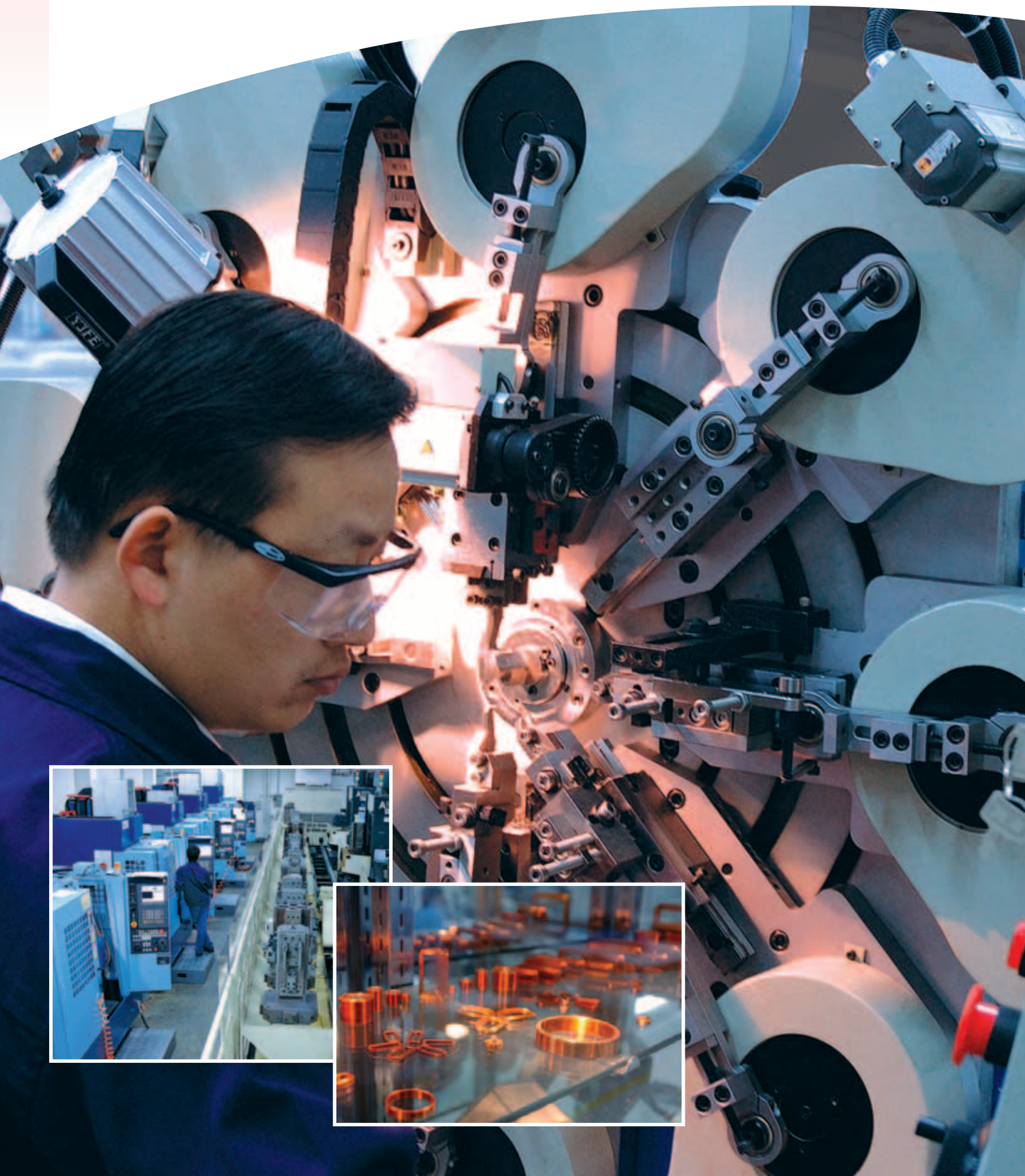
From HK\$1.61 (year end 1988 Initial Public Offering price) to HK\$43.3 (year end 2006 share price, gain of 26.9 times) plus HK\$12.14 (accumulated cash dividends) = total HK\$55.44

由港幣 1.61 元(一九八八年底招股價)至港幣 43.3 元(二零零六年底股價，上升 26.9 倍)加港幣 12.14 元(累積現金股息) = 總額為港幣 55.44 元



Our vertical integration strategy, continuous cost reduction efforts and a constant drive for manufacturing-oriented design enable ASM to offer customers innovative products with good value propositions.

集團的垂直綜合策略，持續致力減省成本及採取以製造為導向的設計模式，使ASM能為客戶提供創新產品及高價值方案。



## CHAIRMAN'S STATEMENT (CONTINUED)

### 主席報告 (續)

#### Appreciation continued

Patrick had also been instrumental in creating the ASM culture that has been the key to the success of the Company in the past and will continue to be in the future. Although he retired on 31 December 2006, Patrick will continue to serve the Company as the Honorary Chairman to guide the succeeding management team for the next 6 months.

The new team took over the helm from 1 January 2007. I am very pleased to have seen a smooth transition so far, and I foresee that the new management team will continue to maintain and improve upon the tremendous growth that we have experienced in the history of the Company. It is management's belief that ASM will continue to outperform our industry peers for many years to come. The board wishes to express its sincere gratitude and appreciation to Mr. Patrick Lam for his invaluable contribution to ASM over the years and wishes him a happy, long and fulfilling retirement.

The Board is also gratified by the invaluable efforts of all our employees who have contributed to the success of the Company. We would once again like to place on record our appreciation of their accomplishments during the past year.

**Arthur H. del Prado**

Chairman

8 March 2007

#### 致謝 續

林先生亦帶領 ASM 建立其獨特的企業文化，成為集團多年來蓬勃發展的關鍵，並引領集團在未來繼續大展鴻圖。儘管林先生已於二零零六年十二月三十一日退休，彼將繼續出任集團的榮譽主席，在未來六個月為繼任之管理層提供意見。

新管理團隊已於二零零七年一月一日正式接任。本人很高興見證交接過程順利進行，並期望新管理層未來將成功延續過往佳績，帶領集團更上一層樓。管理層充滿信心，ASM 未來將能繼續領先同儕。董事會謹此為林師龐先生多年來對 ASM 的貢獻致以衷心謝意，祝願彼退休生活愉快而豐盛。

董事會亦藉此感謝全體員工為集團所付出的努力，並為他們於過去一年的貢獻致以衷心謝意。

主席

**Arthur H. del Prado**

二零零七年三月八日



IC packaging is seen as a technology enabler for consumer applications. ASM's solution-selling strategy helps customers seize the opportunities of consumer product-led growth.

集成電路包裝是作為消費應用產品的必要技術，ASM的綜合解決方案幫助客戶掌握由消費產品主導的行業增長機會。

